

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT2959574

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Chung-Hsiung Wang	07/28/2014
Lang-Yi Chiang	07/28/2014
Wei-Chien Chang	07/28/2014
Yu-Hsin Lin	07/28/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	CYNTEC CO., LTD.
<b>Street Address:</b>	No. 2, R&D 2ND RD., Science-Based Industrial Park
<b>City:</b>	Hsinchu
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14446340
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)997-4517
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	3027291562
<b>Email:</b>	Patent.admin.uspto.cr@naipo.com
<b>Correspondent Name:</b>	WINSTON HSU
<b>Address Line 1:</b>	P.O.BOX 506
<b>Address Line 4:</b>	MERRIFIELD, VIRGINIA 22116
<b>ATTORNEY DOCKET NUMBER:</b>	CYNP0039USA
<b>NAME OF SUBMITTER:</b>	SHELLEY KUO
<b>SIGNATURE:</b>	/SHELLEY KUO/
<b>DATE SIGNED:</b>	07/30/2014
<b>Total Attachments: 2</b>	
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source=2017663#page2.tif	

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Chung-Hsiung Wang Nationality: TW

Name: Lang-Yi Chiang Nationality: TW

Name: Wei-Chien Chang Nationality: TW

Name: Yu-Hsin Lin Nationality: TW

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: CYNTEC CO., LTD.

Address: No. 2, R&D 2ND RD., Science-Based Industrial Park, Hsinchu 30076, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"METHOD OF MANUFACTURING MULTI-LAYER COIL AND MULTI-LAYER COIL DEVICE"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_
- (e) \_\_\_\_\_ International application no. \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this JUL 28 2014 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Chung-Hsiung Wang

Chung-Hsiung Wang

Lang-Yi Chiang

Lang-Yi Chiang

Wei-Chien Chang

Wei-Chien Chang

Yu-Hsin Lin

Yu-Hsin Lin